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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

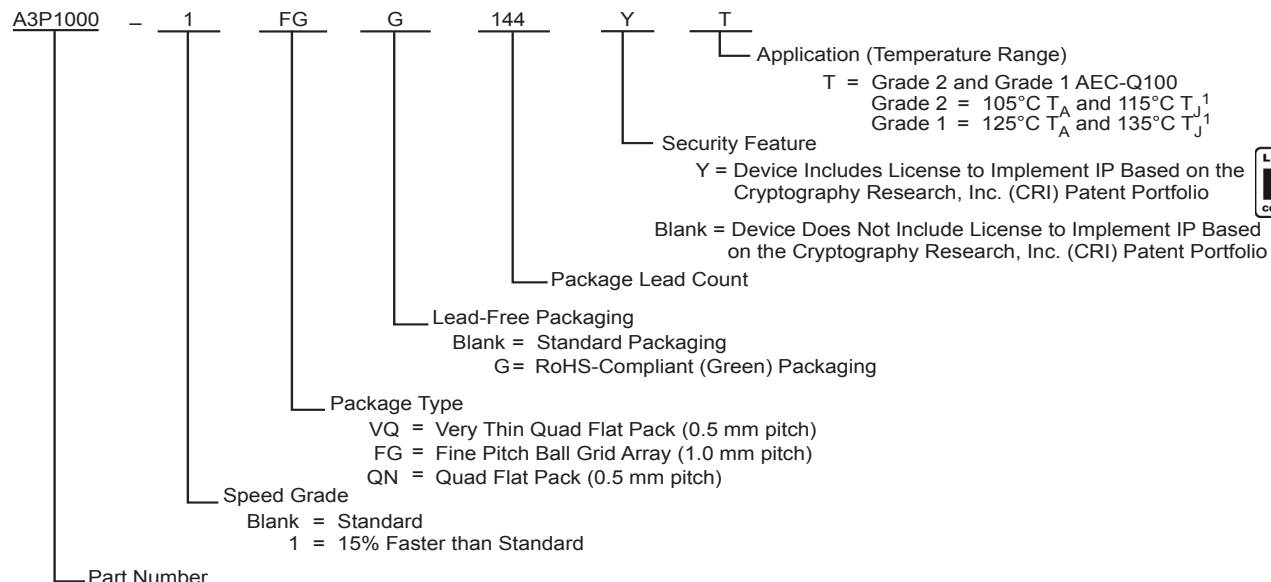
Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Active
Number of LABs/CLBs	-
Number of Logic Elements/Cells	-
Total RAM Bits	36864
Number of I/O	68
Number of Gates	250000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 125°C (TA)
Package / Case	100-TQFP
Supplier Device Package	100-VQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/a3p250-1vqg100t

Automotive ProASIC3 Ordering Information



Automotive ProASIC3 Devices

A3P060	= 60,000 System Gates
A3P125	= 125,000 System Gates
A3P250	= 250,000 System Gates
A3P1000	= 1,000,000 System Gates

Notes:

- T_A = Ambient temperature and T_J = Junction temperature.
- Minimum order quantities apply. Contact your local Microsemi SoC Products Group sales office for details.

Table 2-39 • 3.3 V LVTTTL / 3.3 V LVCMOS High Slew

Automotive-Case Conditions: $T_J = 115^{\circ}\text{C}$, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 3.0 V
Applicable to Advanced I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
4 mA	STD	0.63	8.28	0.05	1.10	0.45	8.44	7.13	1.42	1.37	10.85	9.55	ns
	-1	0.53	7.05	0.04	0.94	0.38	7.18	6.06	1.42	1.37	9.23	8.12	ns
6 mA	STD	0.63	5.31	0.05	1.10	0.45	5.41	4.40	1.60	1.68	7.83	6.82	ns
	-1	0.53	4.52	0.04	0.94	0.38	4.60	3.74	1.60	1.68	6.66	5.80	ns
8 mA	STD	0.63	5.31	0.05	1.10	0.45	5.41	4.40	1.60	1.68	7.83	6.82	ns
	-1	0.53	4.52	0.04	0.94	0.38	4.60	3.74	1.60	1.68	6.66	5.80	ns
12 mA	STD	0.63	3.82	0.05	1.10	0.45	3.89	1.51	3.47	1.88	6.31	2.70	ns
	-1	0.53	3.25	0.04	0.94	0.38	3.31	1.51	2.96	1.88	5.37	2.71	ns
16 mA	STD	0.63	3.60	0.05	1.10	0.45	1.78	1.37	3.53	3.98	2.95	2.57	ns
	-1	0.53	3.07	0.04	0.94	0.38	1.78	1.37	3.00	3.38	2.95	2.57	ns
24 mA	STD	0.63	3.33	0.05	1.10	0.45	1.64	1.13	3.60	4.39	2.81	2.33	ns
	-1	0.53	2.83	0.04	0.94	0.38	1.64	1.13	3.06	3.74	2.82	2.33	ns

Notes:

- Software default selection highlighted in gray.
- For specific junction temperature and voltage supply levels, refer to [Table 2-5 on page 2-5](#) for derating values.

Table 2-40 • 3.3 V LVTTTL / 3.3 V LVCMOS Low Slew

Automotive-Case Conditions: $T_J = 115^{\circ}\text{C}$, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 3.0 V
Applicable to Advanced I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
4 mA	STD	0.63	11.09	0.05	1.10	0.45	11.30	9.63	1.41	1.29	13.72	12.04	ns
	-1	0.53	9.44	0.04	0.94	0.38	9.61	8.19	1.41	1.29	11.67	10.25	ns
6 mA	STD	0.63	7.87	0.05	1.10	0.45	8.02	6.80	1.59	1.59	10.43	9.22	ns
	-1	0.53	6.69	0.04	0.94	0.38	6.82	5.78	1.59	1.60	8.88	7.84	ns
8 mA	STD	0.63	7.87	0.05	1.10	0.45	8.02	6.80	1.59	1.59	10.43	9.22	ns
	-1	0.53	6.69	0.04	0.94	0.38	6.82	5.78	1.59	1.60	8.88	7.84	ns
12 mA	STD	0.63	6.04	0.05	1.10	0.45	6.15	5.27	1.71	1.79	8.57	7.69	ns
	-1	0.53	5.14	0.04	0.94	0.38	5.23	4.48	1.71	1.79	7.29	6.54	ns
16 mA	STD	0.63	5.63	0.05	1.10	0.45	5.74	4.94	1.74	1.84	8.16	7.36	ns
	-1	0.53	4.79	0.04	0.94	0.38	4.88	4.20	1.74	1.84	6.94	6.26	ns
24 mA	STD	0.63	5.25	0.05	1.10	0.45	5.34	4.92	1.77	2.04	7.76	7.34	ns
	-1	0.53	4.46	0.04	0.94	0.38	4.55	4.18	1.77	2.04	6.60	6.24	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-5 on page 2-5](#) for derating values.

Table 2-48 • 2.5 V LVC MOS High Slew

Automotive-Case Conditions: $T_J = 135^{\circ}\text{C}$, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 2.3 V
Applicable to Standard Plus I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	STD	0.64	9.26	0.05	1.45	0.46	8.28	9.26	1.24	1.12	10.78	11.756	ns
	-1	0.55	7.87	0.04	1.23	0.39	7.05	7.87	1.24	1.13	9.17	10	ns
6 mA	STD	0.64	5.43	0.05	1.45	0.46	5.19	5.43	1.43	1.47	7.69	7.926	ns
	-1	0.55	4.62	0.04	1.23	0.39	4.42	4.62	1.43	1.47	6.55	6.743	ns
12 mA	STD	0.64	3.59	0.05	1.45	0.46	3.65	3.51	1.56	1.69	6.15	6.012	ns
	-1	0.55	3.05	0.04	1.23	0.39	3.11	2.99	1.56	1.69	5.23	5.114	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-5 on page 2-5](#) for derating values.

Table 2-49 • 2.5 V LVC MOS Low Slew

Automotive-Case Conditions: $T_J = 135^{\circ}\text{C}$, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 2.3 V
Applicable to Standard Plus I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	STD	0.64	12.12	0.05	1.45	0.46	11.89	12.12	1.25	1.08	14.39	14.622	ns
	-1	0.55	10.31	0.04	1.23	0.39	10.12	10.31	1.25	1.08	12.24	12.438	ns
6 mA	STD	0.64	8.24	0.05	1.45	0.46	8.39	8.23	1.43	1.42	10.89	10.73	ns
	-1	0.55	7.01	0.04	1.23	0.39	7.14	7.00	1.43	1.42	9.26	9.128	ns
12 mA	STD	0.64	6.30	0.05	1.45	0.46	6.41	6.16	1.56	1.63	8.91	8.656	ns
	-1	0.55	5.35	0.04	1.23	0.39	5.45	5.24	1.56	1.63	7.58	7.364	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-5 on page 2-5](#) for derating values.

Table 2-50 • 2.5 V LVCMOS High Slew

Automotive-Case Conditions: $T_J = 115^{\circ}\text{C}$, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 2.3 V
Applicable to Advanced I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	STD	0.63	9.37	0.05	1.40	0.45	8.47	9.37	1.43	1.21	10.89	11.79	ns
	-1	0.53	7.97	0.04	1.19	0.38	7.21	7.97	1.43	1.21	9.27	10.03	ns
6 mA	STD	0.63	5.59	0.05	1.40	0.45	5.45	5.59	1.63	1.57	7.87	8.01	ns
	-1	0.53	4.75	0.04	1.19	0.38	4.63	4.75	1.63	1.57	6.69	6.81	ns
12 mA	STD	0.63	3.85	0.05	1.40	0.45	3.92	3.71	1.77	1.80	6.34	6.13	ns
	-1	0.53	3.28	0.04	1.19	0.38	3.34	3.16	1.77	1.80	5.39	5.22	ns
16 mA	STD	0.63	3.63	0.05	1.40	0.45	1.79	1.64	3.64	3.84	2.96	2.83	ns
	-1	0.53	3.08	0.04	1.19	0.38	1.79	1.64	3.09	3.27	2.96	2.83	ns
24 mA	STD	0.63	3.34	0.05	1.40	0.45	1.65	1.31	3.72	4.32	2.82	2.50	ns
	-1	0.53	2.84	0.04	1.19	0.38	1.65	1.31	3.16	3.68	2.82	2.50	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-5 on page 2-5](#) for derating values.

Table 2-51 • 2.5 V LVCMOS Low Slew

Automotive-Case Conditions: $T_J = 115^{\circ}\text{C}$, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 2.3 V
Applicable to Advanced I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	STD	0.63	11.73	0.05	1.40	0.45	12.14	12.33	1.43	1.16	14.55	14.75	ns
	-1	0.53	9.98	0.04	1.19	0.38	10.32	10.49	1.43	1.16	12.38	12.55	ns
6 mA	STD	0.63	7.97	0.05	1.40	0.45	8.77	8.45	1.63	1.51	11.19	10.87	ns
	-1	0.53	6.78	0.04	1.19	0.38	7.46	7.19	1.63	1.52	9.52	9.25	ns
12 mA	STD	0.63	6.68	0.05	1.40	0.45	6.81	6.40	1.77	1.74	9.23	8.82	ns
	-1	0.53	5.69	0.04	1.19	0.38	5.79	5.45	1.77	1.74	7.85	7.50	ns
16 mA	STD	0.63	6.24	0.05	1.40	0.45	6.35	5.98	1.80	1.80	8.77	8.40	ns
	-1	0.53	5.30	0.04	1.19	0.38	5.40	5.08	1.80	1.80	7.46	7.14	ns
24 mA	STD	0.63	5.96	0.05	1.40	0.45	5.95	5.96	1.84	2.03	8.37	8.38	ns
	-1	0.53	5.07	0.04	1.19	0.38	5.06	5.07	1.84	2.03	7.12	7.12	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-5 on page 2-5](#) for derating values.

Table 2-58 • 1.8 V LVC MOS Low Slew

Automotive-Case Conditions: $T_J = 135^{\circ}\text{C}$, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 2.3 V
Applicable to Advanced I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	STD	0.64	17.36	0.05	1.45	0.46	15.78	17.36	1.53	0.87	18.28	19.864	ns
	-1	0.55	14.77	0.04	1.23	0.39	13.42	14.77	1.54	0.87	15.55	16.897	ns
4 mA	STD	0.64	11.71	0.05	1.45	0.46	11.64	11.71	1.78	1.48	14.14	14.214	ns
	-1	0.55	9.96	0.04	1.23	0.39	9.90	9.96	1.78	1.48	12.03	12.091	ns
6 mA	STD	0.64	9.00	0.05	1.45	0.46	9.17	8.77	1.95	1.77	11.67	11.267	ns
	-1	0.55	7.66	0.04	1.23	0.39	7.80	7.46	1.95	1.77	9.92	9.585	ns
8 mA	STD	0.64	8.39	0.05	1.45	0.46	8.54	8.16	1.99	1.85	11.04	10.66	ns
	-1	0.55	7.14	0.04	1.23	0.39	7.27	6.94	1.99	1.85	9.40	9.068	ns
12 mA	STD	0.64	8.15	0.05	1.45	0.46	8.09	8.15	2.05	2.14	10.59	10.654	ns
	-1	0.55	6.94	0.04	1.23	0.39	6.88	6.94	2.05	2.14	9.01	9.063	ns
16 mA	STD	0.64	8.15	0.05	1.45	0.46	8.09	8.15	2.05	2.14	10.59	10.654	ns
	-1	0.55	6.94	0.04	1.23	0.39	6.88	6.94	2.05	2.14	9.01	9.063	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-5 on page 2-5](#) for derating values.

Table 2-59 • 1.8 V LVC MOS High Slew

Automotive-Case Conditions: $T_J = 135^{\circ}\text{C}$, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 2.3 V
Applicable to Standard Plus I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	STD	0.64	13.26	0.05	1.36	0.46	9.75	12.67	1.24	0.82	12.26	15.17	ns
	-1	0.55	11.28	0.04	1.16	0.39	8.30	10.78	1.24	0.83	10.43	12.905	ns
4 mA	STD	0.64	7.73	0.05	1.36	0.46	6.13	7.25	1.46	1.41	8.63	9.749	ns
	-1	0.55	6.58	0.04	1.16	0.39	5.21	6.17	1.46	1.41	7.34	8.293	ns
6 mA	STD	0.64	4.97	0.05	1.36	0.46	4.29	4.54	1.62	1.68	6.79	7.039	ns
	-1	0.55	4.23	0.04	1.16	0.39	3.65	3.86	1.62	1.68	5.78	5.987	ns
8 mA	STD	0.64	4.39	0.05	1.36	0.46	4.29	4.54	1.62	1.68	6.79	7.039	ns
	-1	0.55	3.73	0.04	1.16	0.39	3.65	3.86	1.62	1.68	5.78	5.987	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-5 on page 2-5](#) for derating values.

Table 2-60 • 1.8 V LVCMOS Low Slew

Automotive-Case Conditions: $T_J = 135^{\circ}\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 2.3\text{ V}$
Applicable to Standard Plus I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	STD	0.64	17.36	0.05	1.45	0.46	15.09	16.55	1.24	0.79	17.59	19.052	ns
	-1	0.55	14.77	0.04	1.23	0.39	12.84	14.08	1.24	0.79	14.96	16.207	ns
4 mA	STD	0.64	11.71	0.05	1.45	0.46	10.88	11.07	1.47	1.35	13.38	13.567	ns
	-1	0.55	9.96	0.04	1.23	0.39	9.26	9.41	1.47	1.35	11.38	11.541	ns
6 mA	STD	0.64	9.00	0.05	1.45	0.46	8.47	8.18	1.62	1.62	10.97	10.685	ns
	-1	0.55	7.66	0.04	1.23	0.39	7.21	6.96	1.62	1.62	9.33	9.089	ns
8 mA	STD	0.64	8.39	0.05	1.45	0.46	8.47	8.18	1.62	1.62	10.97	10.685	ns
	-1	0.55	7.14	0.04	1.23	0.39	7.21	6.96	1.62	1.62	9.33	9.089	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-5 on page 2-5](#) for derating values.

Table 2-61 • 1.8 V LVCMOS High Slew

Automotive-Case Conditions: $T_J = 115^{\circ}\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 2.3\text{ V}$
Applicable to Advanced I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	STD	0.63	12.83	0.05	1.32	0.45	9.88	12.83	1.48	0.87	12.30	15.25	ns
	-1	0.53	10.92	0.04	1.12	0.38	8.41	10.92	1.48	0.87	10.46	12.97	ns
4 mA	STD	0.63	7.48	0.05	1.32	0.45	6.34	7.48	1.72	1.49	8.76	9.90	ns
	-1	0.53	6.36	0.04	1.12	0.38	5.39	6.36	1.72	1.49	7.45	8.42	ns
6 mA	STD	0.63	4.81	0.05	1.32	0.45	4.52	4.81	1.89	1.77	6.94	7.23	ns
	-1	0.53	4.09	0.04	1.12	0.38	3.85	4.09	1.89	1.77	5.90	6.15	ns
8 mA	STD	0.63	4.25	0.05	1.32	0.45	4.25	4.25	1.92	1.85	6.67	6.66	ns
	-1	0.53	3.61	0.04	1.12	0.38	3.61	3.61	1.93	1.85	5.67	5.67	ns
12 mA	STD	0.63	3.82	0.05	1.32	0.45	1.89	1.63	4.00	4.41	3.06	2.82	ns
	-1	0.53	3.25	0.04	1.12	0.38	1.89	1.63	3.41	3.75	3.06	2.82	ns
16 mA	STD	0.63	3.82	0.05	1.32	0.45	1.89	1.63	4.00	4.41	3.06	2.82	ns
	-1	0.53	3.25	0.04	1.12	0.38	1.89	1.63	3.41	3.75	3.06	2.82	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-5 on page 2-5](#) for derating values.

Fully Registered I/O Buffers with Synchronous Enable and Asynchronous Clear

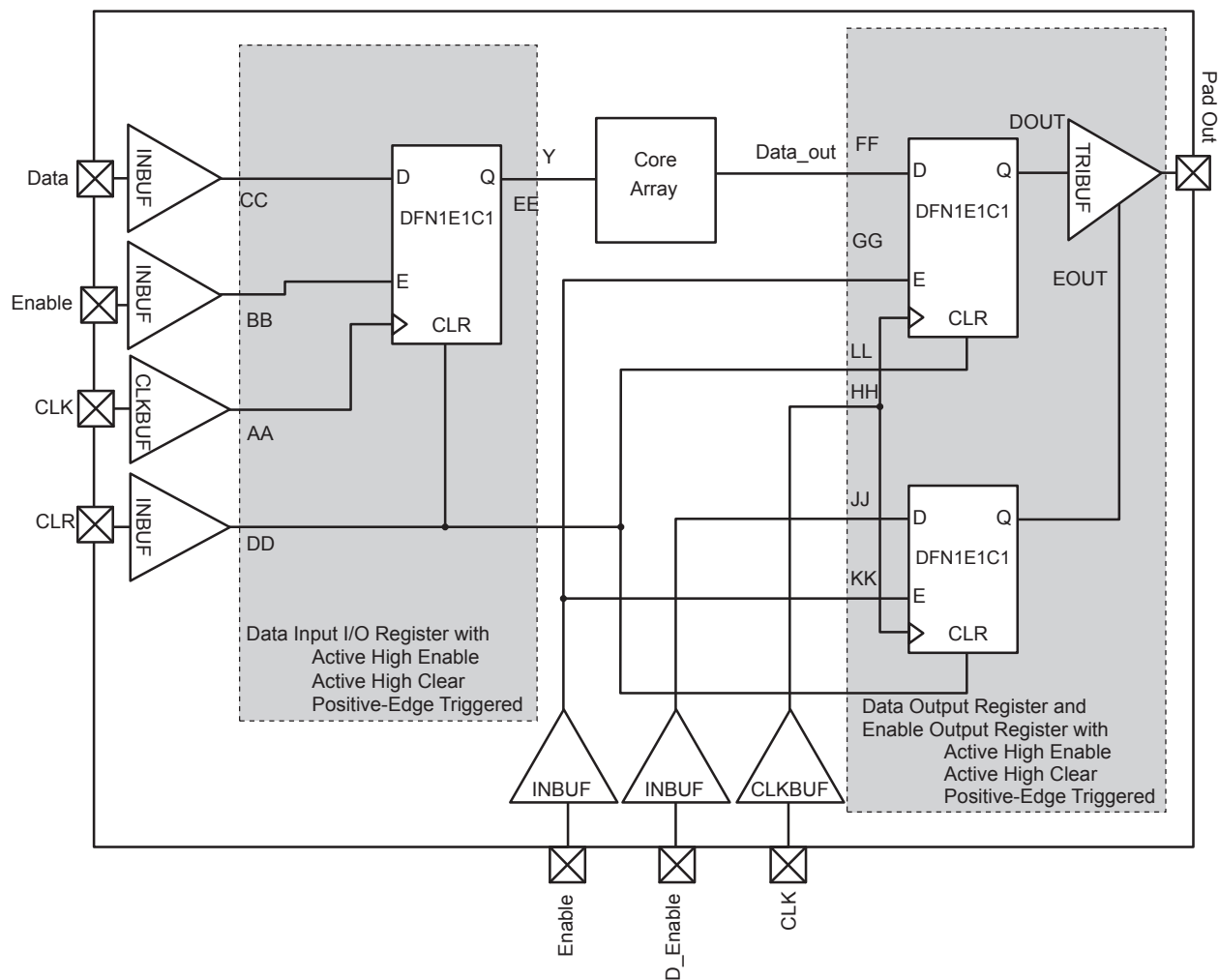
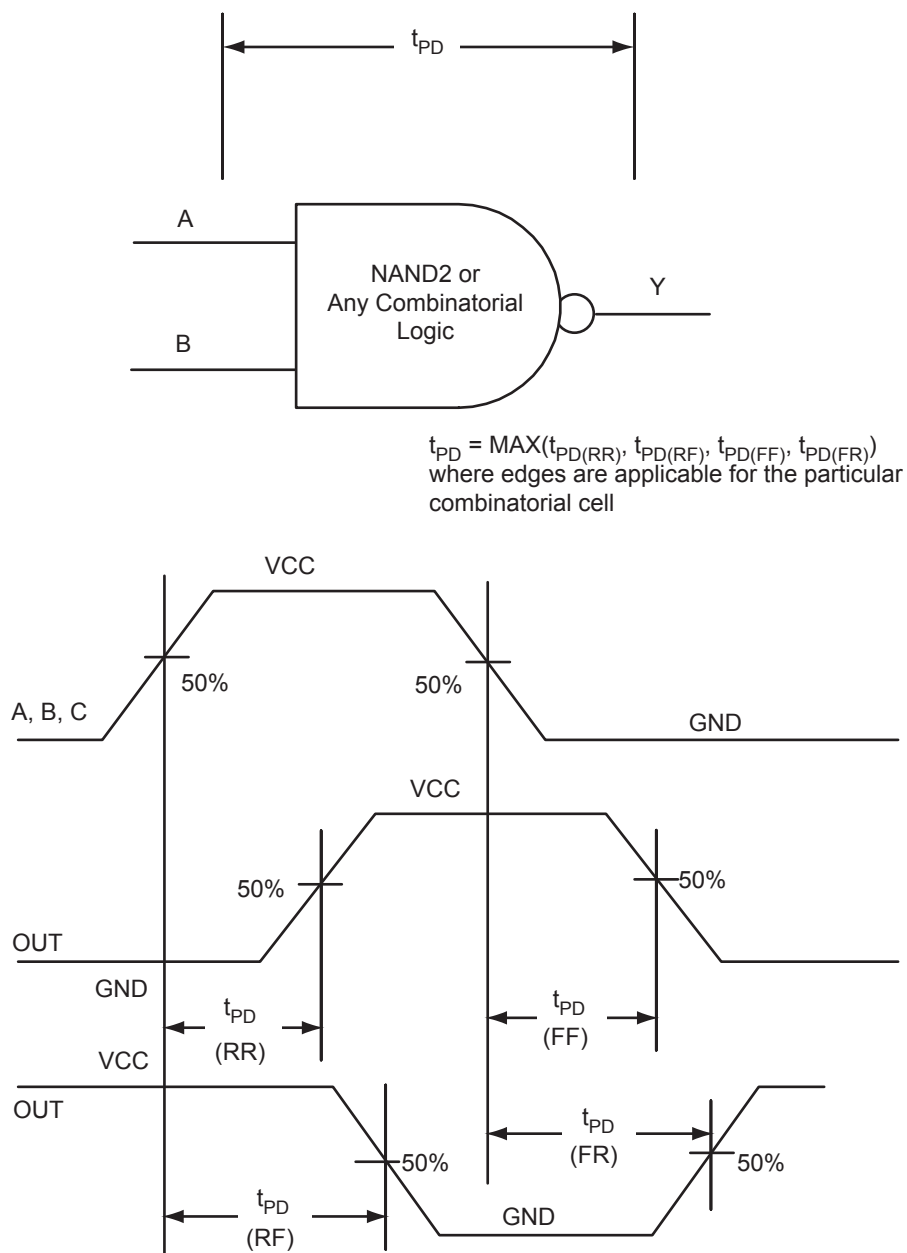


Figure 2-16 • Timing Model of the Registered I/O Buffers with Synchronous Enable and Asynchronous Clear


Figure 2-25 • Timing Model and Waveforms

Global Tree Timing Characteristics

Global clock delays include the central rib delay, the spine delay, and the row delay. Delays do not include I/O input buffer clock delays, as these are I/O standard-dependent, and the clock may be driven and conditioned internally by the CCC module. For more details on clock conditioning capabilities, refer to the "Clock Conditioning Circuits" section on page 2-80. Table 2-114 on page 2-79 to Table 2-125 on page 2-97 present minimum and maximum global clock delays within each device. Minimum and maximum delays are measured with minimum and maximum loading.

Timing Characteristics

Table 2-108 • A3P060 Global Resource

Commercial-Case Conditions: $T_J = 135^{\circ}\text{C}$, $V_{CC} = 1.425\text{ V}$

Parameter	Description	–1		Std.		Units
		Min. ¹	Max. ²	Min. ¹	Max. ²	
t_{RCKL}	Input Low Delay for Global Clock	0.87	1.16	1.02	1.37	ns
t_{RCKH}	Input High Delay for Global Clock	0.86	1.20	1.01	1.42	ns
$t_{RCKMPWH}$	Minimum Pulse Width High for Global Clock	0.80		0.94		ns
$t_{RCKMPWL}$	Minimum Pulse Width Low for Global Clock	0.98		1.15		ns
t_{RCKSW}	Maximum Skew for Global Clock		0.35		0.41	ns

Notes:

1. Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).
2. Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).
3. For specific junction temperature and voltage supply levels, refer to Table 2-5 on page 2-5 for derating values.

Table 2-109 • A3P060 Global Resource

Commercial-Case Conditions: $T_J = 115^{\circ}\text{C}$, $V_{CC} = 1.425\text{ V}$

Parameter	Description	–1		Std.		Units
		Min. ¹	Max. ²	Min. ¹	Max. ²	
t_{RCKL}	Input Low Delay for Global Clock	0.85	1.13	1.00	1.33	ns
t_{RCKH}	Input High Delay for Global Clock	0.84	1.18	0.99	1.38	ns
$t_{RCKMPWH}$	Minimum Pulse Width High for Global Clock	0.80		0.94		ns
$t_{RCKMPWL}$	Minimum Pulse Width Low for Global Clock	0.98		1.15		ns
t_{RCKSW}	Maximum Skew for Global Clock		0.34		0.40	ns

Notes:

1. Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).
2. Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).
3. For specific junction temperature and voltage supply levels, refer to Table 2-5 on page 2-5 for derating values.

Table 2-110 • A3P125 Global Resource
Commercial-Case Conditions: $T_J = 135^{\circ}\text{C}$, $V_{CC} = 1.425\text{ V}$

Parameter	Description	–1		Std.		Units
		Min. ¹	Max. ²	Min. ¹	Max. ²	
t_{RCKL}	Input Low Delay for Global Clock	0.93	1.22	1.09	1.43	ns
t_{RCKH}	Input High Delay for Global Clock	0.92	1.26	1.08	1.49	ns
t_{RCKMPWH}	Minimum Pulse Width High for Global Clock	0.80		0.94		ns
t_{RCKMPWL}	Minimum Pulse Width Low for Global Clock	0.98		1.15		ns
t_{RCKSW}	Maximum Skew for Global Clock		0.35		0.41	ns

Notes:

1. Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).
2. Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).
3. For specific junction temperature and voltage supply levels, refer to [Table 2-5 on page 2-5](#) for derating values.

Table 2-111 • A3P125 Global Resource
Commercial-Case Conditions: $T_J = 115^{\circ}\text{C}$, $V_{CC} = 1.425\text{ V}$

Parameter	Description	–1		Std.		Units
		Min. ¹	Max. ²	Min. ¹	Max. ²	
t_{RCKL}	Input Low Delay for Global Clock	0.90	1.19	1.06	1.40	ns
t_{RCKH}	Input High Delay for Global Clock	0.90	1.23	1.05	1.45	ns
t_{RCKMPWH}	Minimum Pulse Width High for Global Clock	0.80		0.94		ns
t_{RCKMPWL}	Minimum Pulse Width Low for Global Clock	0.98		1.15		ns
t_{RCKSW}	Maximum Skew for Global Clock		0.34		0.40	ns

Notes:

1. Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).
2. Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).
3. For specific junction temperature and voltage supply levels, refer to [Table 2-5 on page 2-5](#) for derating values.

Table 2-112 • A3P250 Global Resource
Commercial-Case Conditions: $T_J = 135^{\circ}\text{C}$, $V_{CC} = 1.425\text{ V}$

Parameter	Description	–1		Std.		Units
		Min. ¹	Max. ²	Min. ¹	Max. ²	
t_{RCKL}	Input Low Delay for Global Clock	0.96	1.25	1.13	1.47	ns
t_{RCKH}	Input High Delay for Global Clock	0.94	1.28	1.10	1.51	ns
$t_{RCKMPWH}$	Minimum Pulse Width High for Global Clock	0.80		0.94		ns
$t_{RCKMPWL}$	Minimum Pulse Width Low for Global Clock	0.98		1.15		ns
t_{RCKSW}	Maximum Skew for Global Clock		0.35		0.41	ns

Notes:

1. Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).
2. Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).
3. For specific junction temperature and voltage supply levels, refer to [Table 2-5 on page 2-5](#) for derating values.

Table 2-113 • A3P250 Global Resource
Commercial-Case Conditions: $T_J = 115^{\circ}\text{C}$, $V_{CC} = 1.425\text{ V}$

Parameter	Description	–1		Std.		Units
		Min. ¹	Max. ²	Min. ¹	Max. ²	
t_{RCKL}	Input Low Delay for Global Clock	0.94	1.22	1.10	1.44	ns
t_{RCKH}	Input High Delay for Global Clock	0.92	1.25	1.08	1.47	ns
$t_{RCKMPWH}$	Minimum Pulse Width High for Global Clock	0.80		0.94		ns
$t_{RCKMPWL}$	Minimum Pulse Width Low for Global Clock	0.98		1.15		ns
t_{RCKSW}	Maximum Skew for Global Clock		0.34		0.40	ns

Notes:

1. Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).
2. Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).
3. For specific junction temperature and voltage supply levels, refer to [Table 2-5 on page 2-5](#) for derating values.

Timing Waveforms

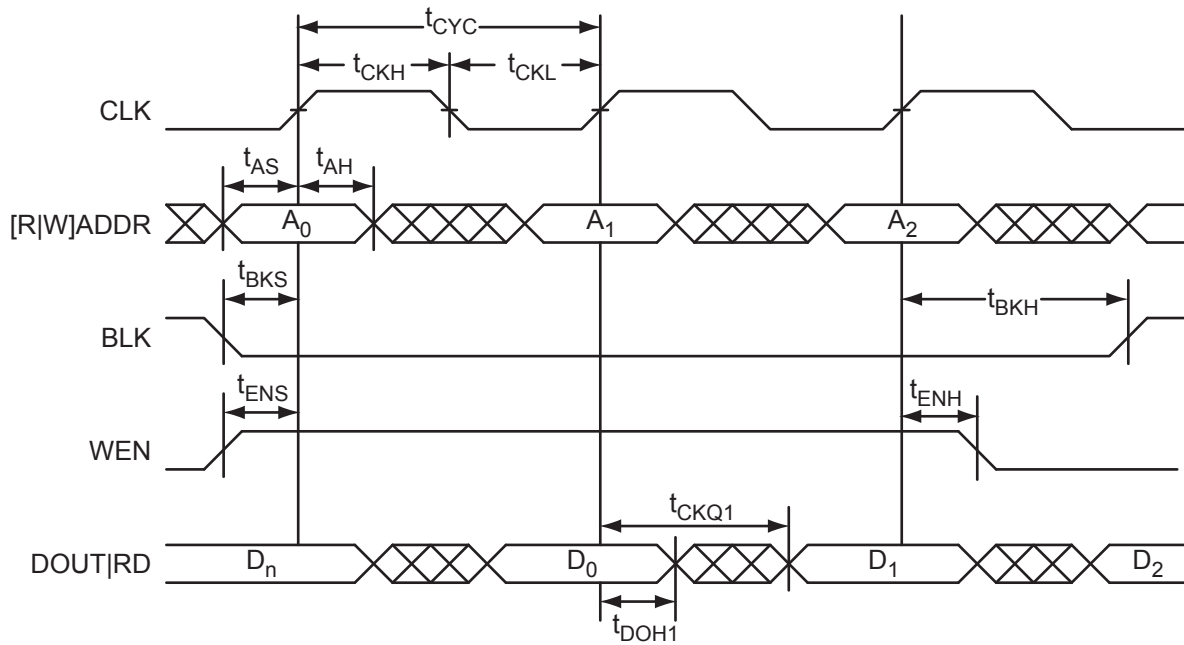


Figure 2-31 • RAM Read for Pass-Through Output. Applicable to Both RAM4K9 and RAM512x18.

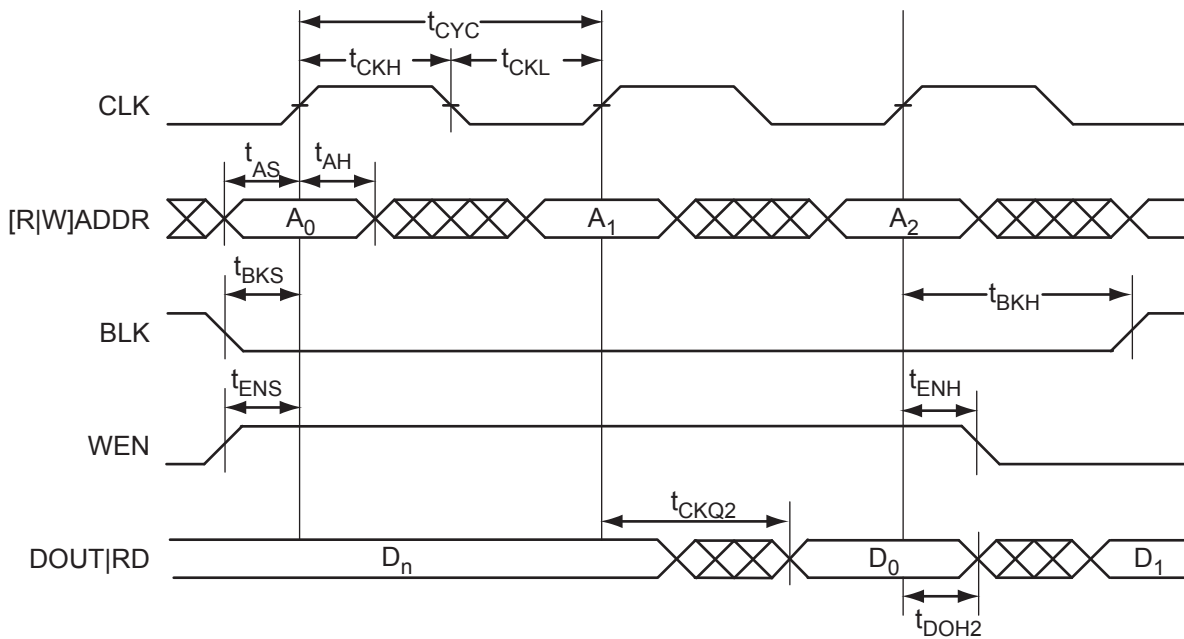
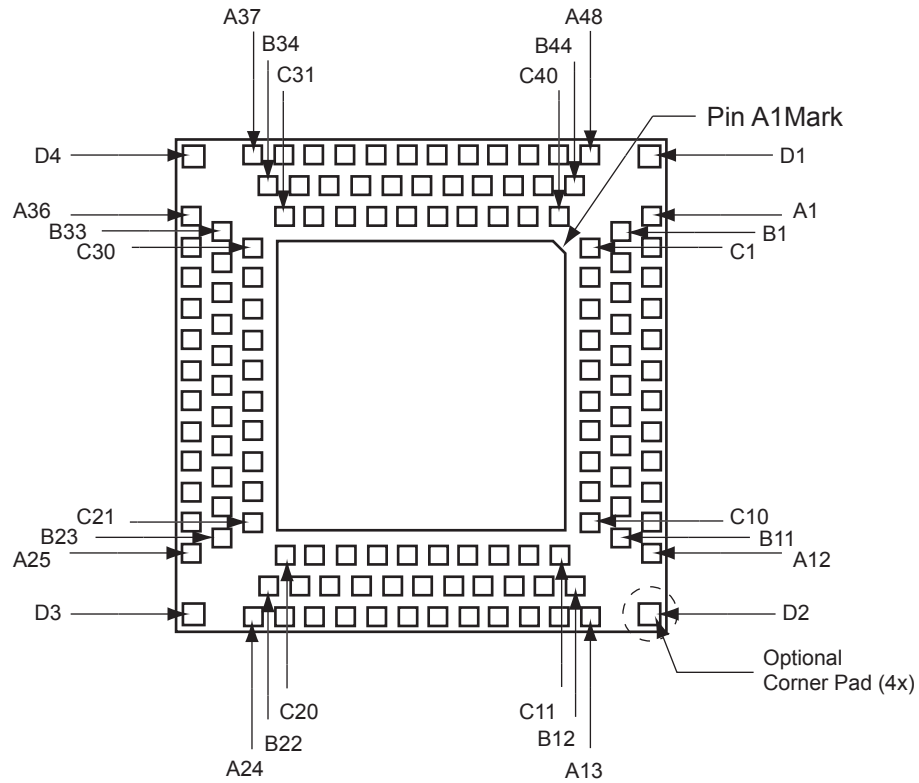


Figure 2-32 • RAM Read for Pipelined Output. Applicable to Both RAM4K9 and RAM512x18.

VQ100		VQ100		VQ100	
Pin Number	A3P250 Function	Pin Number	A3P250 Function	Pin Number	A3P250 Function
1	GND	35	IO85RSB2	69	IO43NDB1
2	GAA2/IO118UDB3	36	IO84RSB2	70	GBC2/IO43PDB1
3	IO118VDB3	37	VCC	71	GBB2/IO42PSB1
4	GAB2/IO117UDB3	38	GND	72	IO41NDB1
5	IO117VDB3	39	VCCIB2	73	GBA2/IO41PDB1
6	GAC2/IO116UDB3	40	IO77RSB2	74	VMV1
7	IO116VDB3	41	IO74RSB2	75	GNDQ
8	IO112PSB3	42	IO71RSB2	76	GBA1/IO40RSB0
9	GND	43	GDC2/IO63RSB2	77	GBA0/IO39RSB0
10	GFB1/IO109PDB3	44	GDB2/IO62RSB2	78	GBB1/IO38RSB0
11	GFB0/IO109NDB3	45	GDA2/IO61RSB2	79	GBB0/IO37RSB0
12	VCOMPLF	46	GNDQ	80	GBC1/IO36RSB0
13	GFA0/IO108NPB3	47	TCK	81	GBC0/IO35RSB0
14	VCCPLF	48	TDI	82	IO29RSB0
15	GFA1/IO108PPB3	49	TMS	83	IO27RSB0
16	GFA2/IO107PSB3	50	VMV2	84	IO25RSB0
17	VCC	51	GND	85	IO23RSB0
18	VCCIB3	52	VPUMP	86	IO21RSB0
19	GFC2/IO105PSB3	53	NC	87	VCCIB0
20	GEC1/IO100PDB3	54	TDO	88	GND
21	GEC0/IO100NDB3	55	TRST	89	VCC
22	GEA1/IO98PDB3	56	VJTAG	90	IO15RSB0
23	GEA0/IO98NDB3	57	GDA1/IO60USB1	91	IO13RSB0
24	VMV3	58	GDC0/IO58VDB1	92	IO11RSB0
25	GNDQ	59	GDC1/IO58UDB1	93	GAC1/IO05RSB0
26	GEA2/IO97RSB2	60	IO52NDB1	94	GAC0/IO04RSB0
27	GEB2/IO96RSB2	61	GCB2/IO52PDB1	95	GAB1/IO03RSB0
28	GEC2/IO95RSB2	62	GCA1/IO50PDB1	96	GAB0/IO02RSB0
29	IO93RSB2	63	GCA0/IO50NDB1	97	GAA1/IO01RSB0
30	IO92RSB2	64	GCC0/IO48NDB1	98	GAA0/IO00RSB0
31	IO91RSB2	65	GCC1/IO48PDB1	99	GNDQ
32	IO90RSB2	66	VCCIB1	100	VMV0
33	IO88RSB2	67	GND		
34	IO86RSB2	68	VCC		

QN132



Notes:

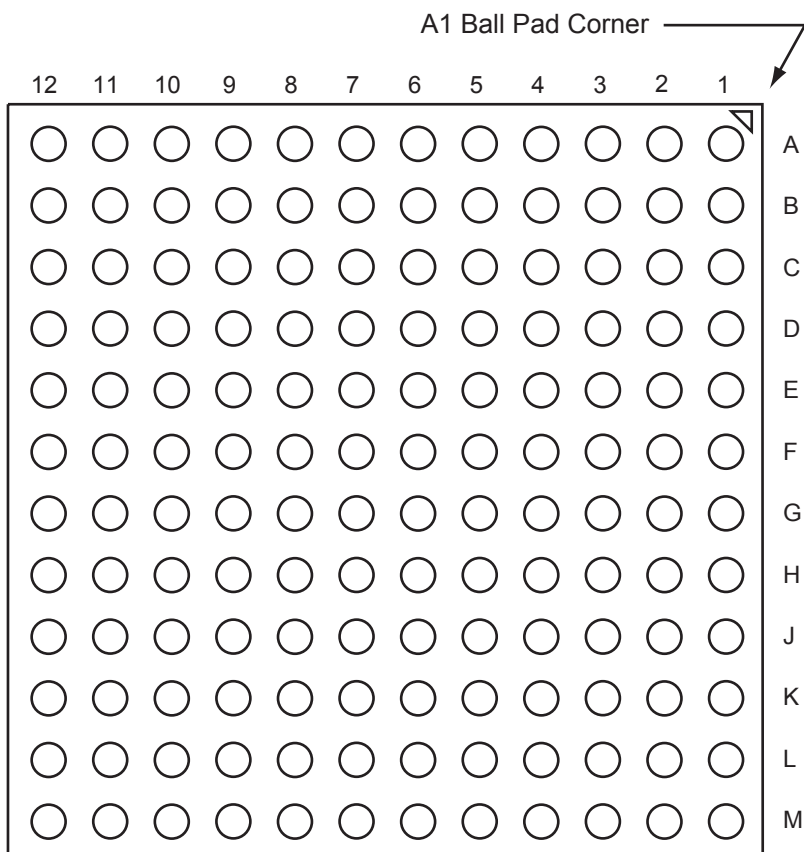
1. This is the bottom view of the package.
2. The die attach paddle center of the package is tied to ground (GND).

Note

For Package Manufacturing and Environmental information, visit the Resource Center at <http://www.actel.com/products/solutions/package/docs.aspx>.

QN132	
Pin Number	A3P125 Function
C17	IO83RSB1
C18	VCCIB1
C19	TCK
C20	VMV1
C21	VPUMP
C22	VJTAG
C23	VCCIB0
C24	NC
C25	NC
C26	GCA1/IO55RSB0
C27	GCC0/IO52RSB0
C28	VCCIB0
C29	IO42RSB0
C30	GNDQ
C31	GBA1/IO40RSB0
C32	GBB0/IO37RSB0
C33	VCC
C34	IO24RSB0
C35	IO19RSB0
C36	IO16RSB0
C37	IO10RSB0
C38	VCCIB0
C39	GAB1/IO03RSB0
C40	VMV0
D1	GND
D2	GND
D3	GND
D4	GND

FG144



Note: This is the bottom view of the package.

Note

For Package Manufacturing and Environmental information, visit the Resource Center at <http://www.actel.com/products/solutions/package/docs.aspx>.

FG144	
Pin Number	A3P060 Function
K1	GEB0/IO74RSB1
K2	GEA1/IO73RSB1
K3	GEA0/IO72RSB1
K4	GEA2/IO71RSB1
K5	IO65RSB1
K6	IO64RSB1
K7	GND
K8	IO57RSB1
K9	GDC2/IO56RSB1
K10	GND
K11	GDA0/IO50RSB0
K12	GDB0/IO48RSB0
L1	GND
L2	VMV1
L3	GEB2/IO70RSB1
L4	IO67RSB1
L5	VCCIB1
L6	IO62RSB1
L7	IO59RSB1
L8	IO58RSB1
L9	TMS
L10	VJTAG
L11	VMV1
L12	TRST
M1	GNDQ
M2	GEC2/IO69RSB1
M3	IO68RSB1
M4	IO66RSB1
M5	IO63RSB1
M6	IO61RSB1
M7	IO60RSB1
M8	NC
M9	TDI
M10	VCCIB1
M11	VPUMP
M12	GNDQ

FG144	
Pin Number	A3P250 Function
K1	GEB0/IO99NDB3
K2	GEA1/IO98PDB3
K3	GEA0/IO98NDB3
K4	GEA2/IO97RSB2
K5	IO90RSB2
K6	IO84RSB2
K7	GND
K8	IO66RSB2
K9	GDC2/IO63RSB2
K10	GND
K11	GDA0/IO60VDB1
K12	GDB0/IO59VDB1
L1	GND
L2	VMV3
L3	GEB2/IO96RSB2
L4	IO91RSB2
L5	VCCIB2
L6	IO82RSB2
L7	IO80RSB2
L8	IO72RSB2
L9	TMS
L10	VJTAG
L11	VMV2
L12	TRST
M1	GNDQ
M2	GEC2/IO95RSB2
M3	IO92RSB2
M4	IO89RSB2
M5	IO87RSB2
M6	IO85RSB2
M7	IO78RSB2
M8	IO76RSB2
M9	TDI
M10	VCCIB2
M11	VPUMP
M12	GNDQ

FG144		FG144		FG144	
Pin Number	A3P1000 Function	Pin Number	A3P1000 Function	Pin Number	A3P1000 Function
A1	GNDQ	D1	IO213PDB3	G1	GFA1/IO207PPB3
A2	VMV0	D2	IO213NDB3	G2	GND
A3	GAB0/IO02RSB0	D3	IO223NDB3	G3	VCCPLF
A4	GAB1/IO03RSB0	D4	GAA2/IO225PPB3	G4	GFA0/IO207NPB3
A5	IO10RSB0	D5	GAC0/IO04RSB0	G5	GND
A6	GND	D6	GAC1/IO05RSB0	G6	GND
A7	IO44RSB0	D7	GBC0/IO72RSB0	G7	GND
A8	VCC	D8	GBC1/IO73RSB0	G8	GDC1/IO111PPB1
A9	IO69RSB0	D9	GBB2/IO79PDB1	G9	IO96NDB1
A10	GBA0/IO76RSB0	D10	IO79NDB1	G10	GCC2/IO96PDB1
A11	GBA1/IO77RSB0	D11	IO80NPB1	G11	IO95NDB1
A12	GNDQ	D12	GCB1/IO92PPB1	G12	GCB2/IO95PDB1
B1	GAB2/IO224PDB3	E1	VCC	H1	VCC
B2	GND	E2	GFC0/IO209NDB3	H2	GFB2/IO205PDB3
B3	GAA0/IO00RSB0	E3	GFC1/IO209PDB3	H3	GFC2/IO204PSB3
B4	GAA1/IO01RSB0	E4	VCCIB3	H4	GEC1/IO190PDB3
B5	IO13RSB0	E5	IO225NPB3	H5	VCC
B6	IO26RSB0	E6	VCCIB0	H6	IO105PDB1
B7	IO35RSB0	E7	VCCIB0	H7	IO105NDB1
B8	IO60RSB0	E8	GCC1/IO91PDB1	H8	GDB2/IO115RSB2
B9	GBB0/IO74RSB0	E9	VCCIB1	H9	GDC0/IO111NPB1
B10	GBB1/IO75RSB0	E10	VCC	H10	VCCIB1
B11	GND	E11	GCA0/IO93NDB1	H11	IO101PSB1
B12	VMV1	E12	IO94NDB1	H12	VCC
C1	IO224NDB3	F1	GFB0/IO208NPB3	J1	GEB1/IO189PDB3
C2	GFA2/IO206PPB3	F2	VCOMPLF	J2	IO205NDB3
C3	GAC2/IO223PDB3	F3	GFB1/IO208PPB3	J3	VCCIB3
C4	VCC	F4	IO206NPB3	J4	GEC0/IO190NDB3
C5	IO16RSB0	F5	GND	J5	IO160RSB2
C6	IO29RSB0	F6	GND	J6	IO157RSB2
C7	IO32RSB0	F7	GND	J7	VCC
C8	IO63RSB0	F8	GCC0/IO91NDB1	J8	TCK
C9	IO66RSB0	F9	GCB0/IO92NPB1	J9	GDA2/IO114RSB2
C10	GBA2/IO78PDB1	F10	GND	J10	TDO
C11	IO78NDB1	F11	GCA1/IO93PDB1	J11	GDA1/IO113PDB1
C12	GBC2/IO80PPB1	F12	GCA2/IO94PDB1	J12	GDB1/IO112PDB1